

MBR1635, MBR1645, MBRB1645

MBR1645 is a Preferred Device

SWITCHMODE™ Power Rectifiers 16 A, 35 and 45 V

These state-of-the-art devices use the Schottky Barrier principle with a platinum barrier metal.

Features

- Guard-ring for Stress Protection
- Low Forward Voltage
- 175°C Operating Junction Temperature
- Pb-Free Packages are Available*

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 1.9 Grams for TO-220
1.7 Grams for D²PAK
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes:
260°C Max. for 10 Seconds

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}		V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_R	35 45 45	
		MBR1635 MBR1645 MBRB1645	
Average Rectified Forward Current (Rated V_R , $T_C = 125^\circ\text{C}$)	$I_{F(AV)}$	16	A
Peak Repetitive Forward Current, (Rated V_R , Square Wave, 20 kHz, $T_C = 125^\circ\text{C}$)	I_{FRM}	32	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	150	A
Peak Repetitive Reverse Surge Current (2.0 μs , 1.0 kHz)	I_{RRM}	1.0	A
Storage Temperature Range	T_{stg}	-65 to +175	°C
Operating Junction Temperature (Note 1)	T_J	-65 to +175	°C
Voltage Rate of Change (Rated V_R)	dv/dt	10,000	V/ μs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

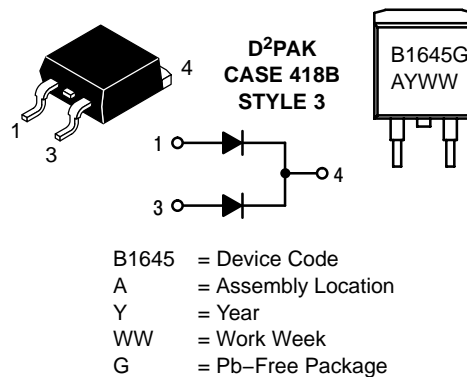
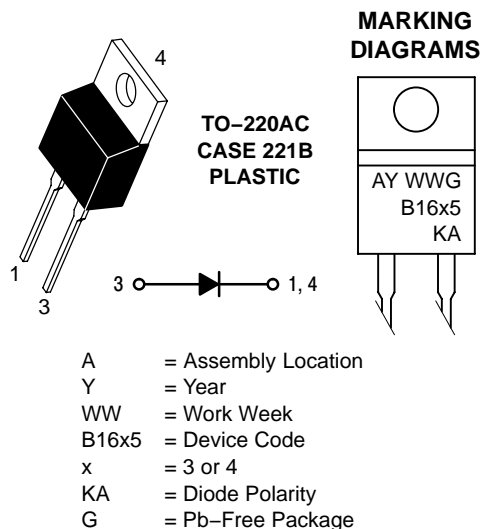
1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_J/dT_J < 1/R_{\theta JA}$.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



ON Semiconductor®

<http://onsemi.com>



ORDERING INFORMATION

Device	Package	Shipping
MBR1635	TO-220	50 Units / Rail
MBR1635G	TO-220 (Pb-Free)	50 Units / Rail
MBR1645	TO-220	50 Units / Rail
MBR1645G	TO-220 (Pb-Free)	50 Units / Rail
MBRB1645T4G	D ² PAK (Pb-Free)	800 Units / Rail

Preferred devices are recommended choices for future use and best overall value.

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THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.5	$^{\circ}\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 2) ($i_F = 16$ Amps, $T_C = 125^{\circ}\text{C}$) ($i_F = 16$ Amps, $T_C = 25^{\circ}\text{C}$)	v_F	0.57 0.63	V
Maximum Instantaneous Reverse Current (Note 2) (Rated dc Voltage, $T_C = 125^{\circ}\text{C}$) (Rated dc Voltage, $T_C = 25^{\circ}\text{C}$)	i_R	40 0.2	mA

2. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

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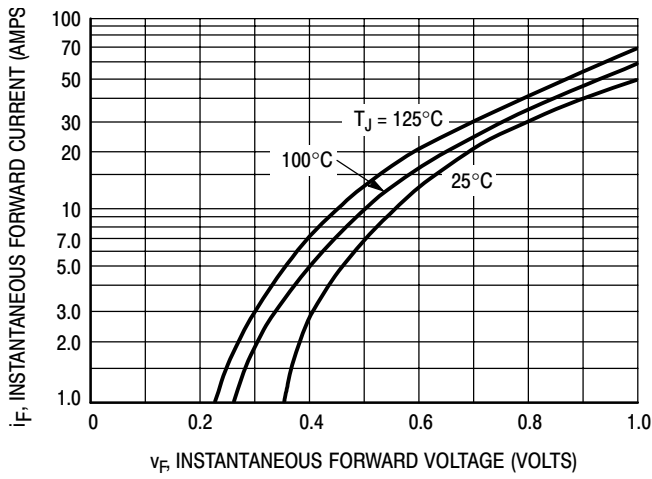


Figure 1. Typical Forward Voltage

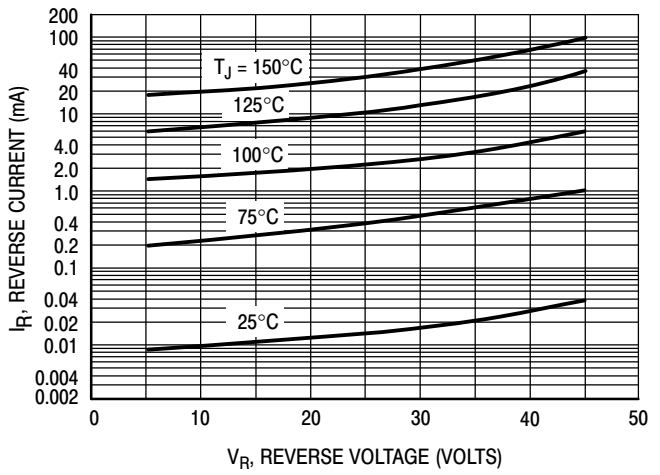


Figure 2. Typical Reverse Current

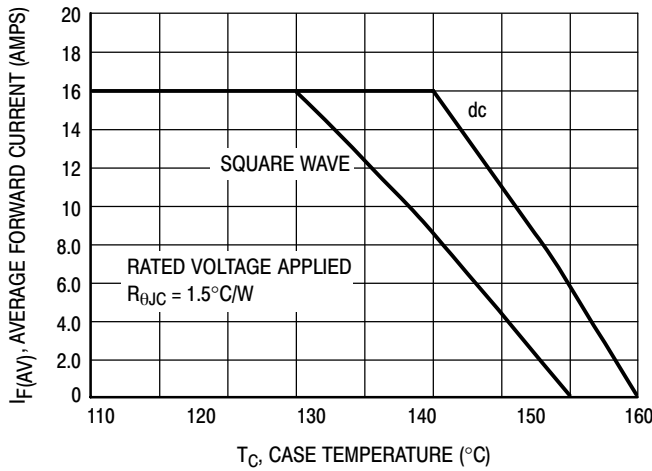


Figure 3. Current Derating, Case

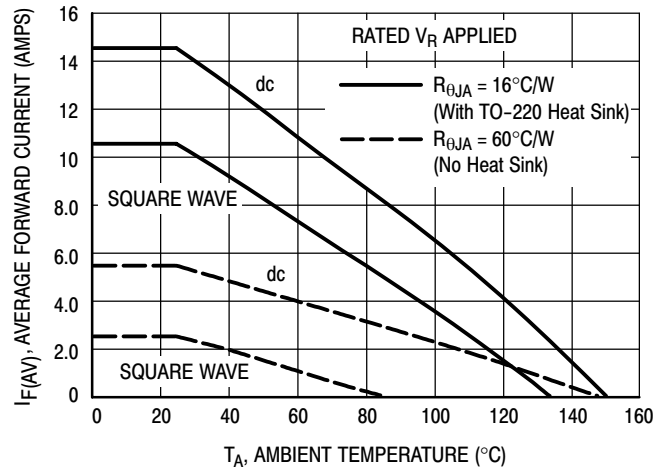


Figure 4. Current Derating, Ambient

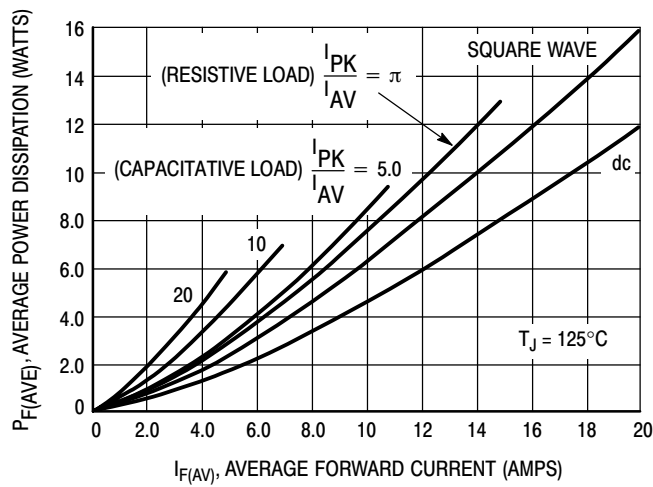
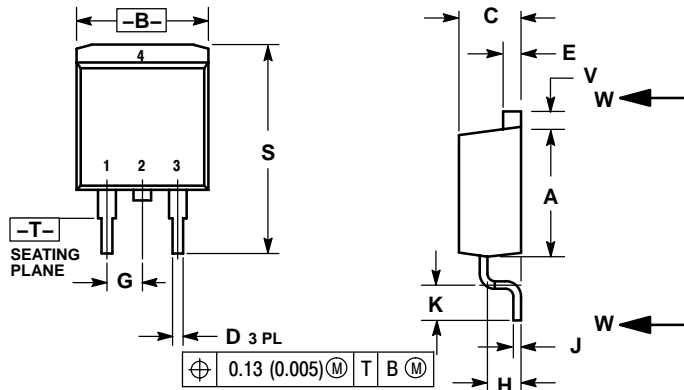


Figure 5. Forward Power Dissipation

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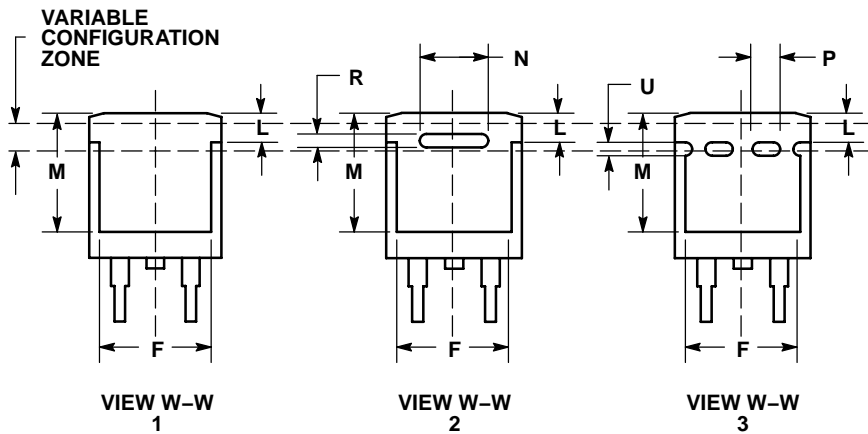
PACKAGE DIMENSIONS

D²PAK
CASE 418B-04
ISSUE J



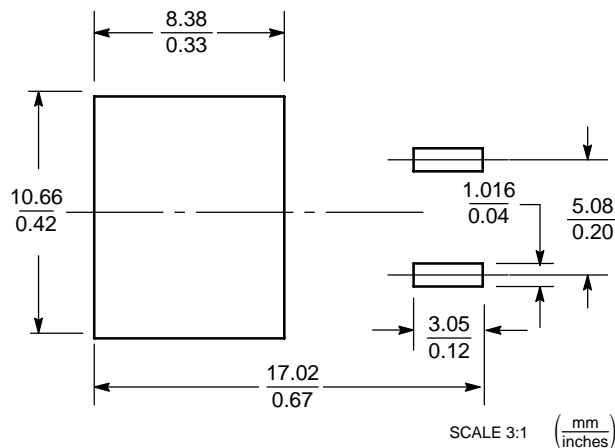
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197 REF		5.00 REF	
P	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40



- STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

SOLDERING FOOTPRINT*



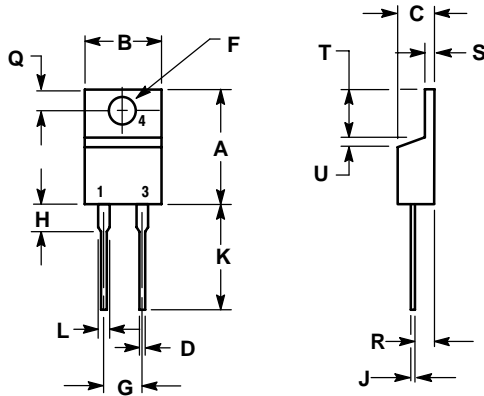
SCALE 3:1 (mm/inches)

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PACKAGE DIMENSIONS


TO-220
PLASTIC
CASE 221B-04
ISSUE D



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.595	0.620	15.11	15.75
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.82
D	0.025	0.035	0.64	0.89
F	0.142	0.147	3.61	3.73
G	0.190	0.210	4.83	5.33
H	0.110	0.130	2.79	3.30
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.14	1.52
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.14	1.39
T	0.235	0.255	5.97	6.48
U	0.000	0.050	0.000	1.27

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